

# Copper Bath SLOTOCOUP HL 10 for horizontal reel-to-reel plating lines with insoluble anodes

Copper Bath SLOTOCOUP HL 10 is used for plating of printed circuit boards in horizontal reel-to-reel plating lines with insoluble anodes. It is especially suitable for periodic current reverse (reverse pulse plating).

Copper Bath SLOTOCOUP HL 10 deposits fine grained, ductile coatings with excellent metal distribution. Make-up and operation of the electrolyte is carried out with two additives.

Operating the Copper Bath SLOTOCOUP HL 10 with periodic reverse pulse plating may shorten the plating time significantly with an excellent metal distribution at the same time.

Copper Bath SLOTOCOUP HL 10 can also be operated with direct current (Direct Current Plating) and then provides bright, fine grained and ductile copper deposits.

The information in this data sheet is based on laboratory as well as practical experience. Figures quoted for operating limits and replenishment quantities are for guidance. Actual values necessary will depend on the components being plated (material and geometry), their application and plating plant conditions.

#### Important:

Please read these instructions carefully and follow recommendations given. We reserve the right to make technical changes as necessary. In the interests of safety, please pay attention to the R- and S- phrases on the labels of the containers. The minimum shelf life of the additives is printed on the label of the container. The current IMDS number of the layer deposited from the process can be found on the internet at [www.schloetter.com/downloads](http://www.schloetter.com/downloads).

For the storage of chemical products only the TRGS 514 and TRGS 515 regulations must be followed. The Hazardous Goods Regulation (ADR/GGVS) is only valid **for transportation** and must not be applied to storage.

